SCBS466 - JANUARY 1991 - REVISED OCTOBER 1992

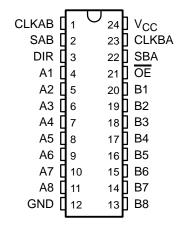
- State-of-the-Art EPIC-IIB™ BiCMOS Design Significantly Reduces Power Dissipation
- ESD Protection Exceeds 2000 V Per MIL-STD-883C, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17
- Typical V_{OLP} (Output Ground Bounce) < 1 V at V_{CC} = 5 V, T_A = 25°C
- High-Drive Outputs (-32-mA I_{OH}, 64-mA I_{OL})
- Multiplexed Real-Time and Stored Data
- Inverting Data Paths
- Package Options Include Plastic Small-Outline Packages (DW), Ceramic Chip Carriers (FK), and Standard Plastic and Ceramic 300-mil DIPs (JT, NT)

description

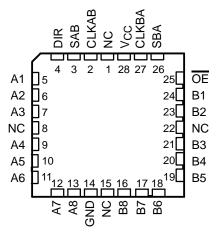
These devices consist of bus transceiver circuits, D-type flip-flops, and control circuitry arranged for multiplexed transmission of data directly from the input bus or from the internal registers. Data on the A or B bus is clocked into the registers on the low-to-high transition of the appropriate clock (CLKAB or CLKBA) input. Figure 1 illustrates the four fundamental bus-management functions that can be performed with the 'ABT648.

Output-enable (\overline{OE}) and direction-control (DIR) inputs are provided to control the transceiver functions. In the transceiver mode, data present at the high-impedance port may be stored in either register or in both.

SN54ABT648 ... JT PACKAGE SN74ABT648 ... DW OR NT PACKAGE (TOP VIEW)



SN54ABT648...FK PACKAGE (TOP VIEW)



NC - No internal connection

The select-control (SAB and SBA) inputs can multiplex stored and real-time (transparent mode) data. The direction control (DIR) determines which bus will receive data when \overline{OE} is low. In the isolation mode (\overline{OE} high), A data may be stored in one register and/or B data may be stored in the other register.

When an output function is disabled, the input function is still enabled and may be used to store and transmit data. Only one of the two buses, A or B, may be driven at a time.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ABT648 is characterized for operation over the full military temperature range of -55° C to 125° C. The SN74ABT648 is characterized for operation from -40° C to 85° C.

EPIC-IIB is a trademark of Texas Instruments Incorporated



SCBS466 - JANUARY 1991 - REVISED OCTOBER 1992

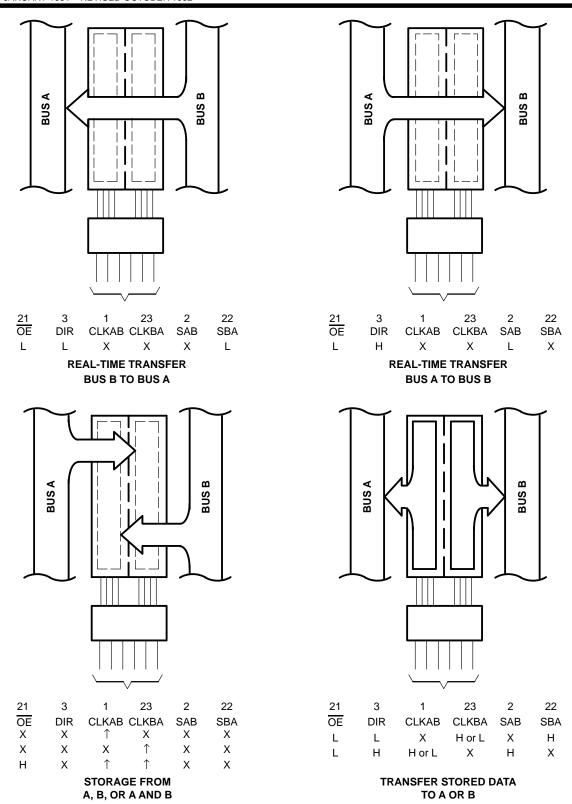


Figure 1. Bus-Management Functions

Pin numbers shown are for DW, JT, and NT packages.



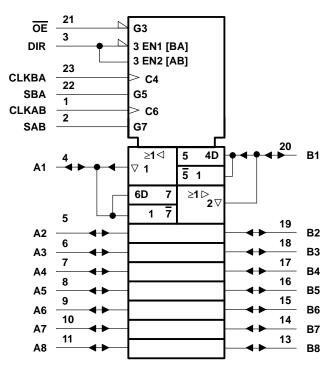
SCBS466 - JANUARY 1991 - REVISED OCTOBER 1992

FUNCTION TABLE

INPUTS						DAT	A I/O	ODERATION OR FUNCTION		
ŌĒ	DIR	CLKAB	CLKBA	SAB	SBA	A1 THRU A8	B1 THRU B8	OPERATION OR FUNCTION		
Х	Х	1	Х	Х	Х	Input	Unspecified [†]	Store A, B unspecified [†]		
Х	Χ	Χ	↑	Χ	Χ	Unspecified [†]	Input	Store B, A unspecified [†]		
Н	Х	1	↑	Х	Х	Input	Input	Store A and B data		
Н	Χ	H or L	H or L	Χ	Χ	Input	Input	Isolation, hold storage		
L	L	Х	Χ	Х	L	Output	Input	Real-time B data to A Bus		
L	L	Χ	H or L	Χ	Н	Output	Input	Stored \overline{B} data to A Bus		
L	Н	Х	Х	L	Χ	Input	Output	Real-time \overline{A} data to B Bus		
L	Н	H or L	Χ	Н	Χ	Input	Output	Stored \overline{A} data to B Bus		

[†] The data output functions may be enabled or disabled by various signals at the $\overline{\text{OE}}$ and DIR inputs. Data input functions are always enabled; i.e., data at the bus pins will be stored on every low-to-high transition of the clock inputs.

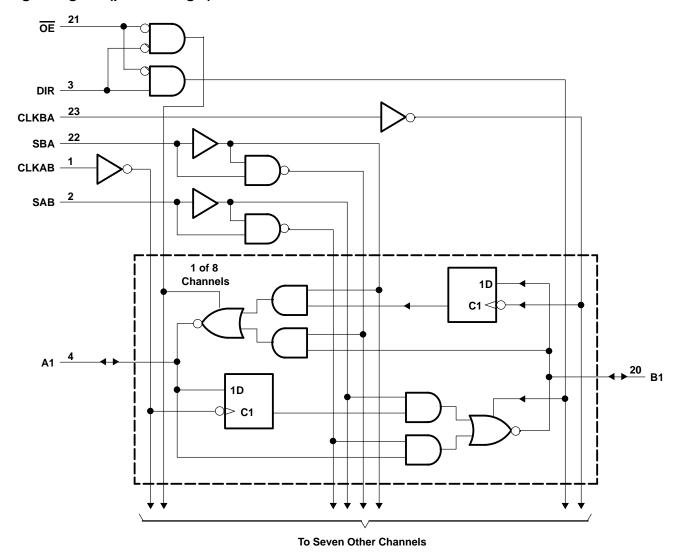
logic symbol‡



[‡] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the DW, JT, and NT packages.



logic diagram (positive logic)



Pin numbers shown are for DW, JT, and NT packages.

PRODUCT PREVIEW

SCBS466 - JANUARY 1991 - REVISED OCTOBER 1992

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	-0.5 V to 7 V
Input voltage range, V _I (except I/O ports) (see Note 1)	-0.5 V to 7 V
Voltage range applied to any output in the high state or power-off state, VO	-0.5 V to 5.5 V
Current into any output in the low state, IO: SN54ABT648	96 mA
SN74ABT648	128 mA
Input clamp current, I _{IK} (V _I < 0)	–18 mA
Output clamp current, I _{OK} (V _O < 0)	50 mA
Maximum power dissipation at T _A = 55°C (in still air): DW package	1 W
NT package	1.3 W
Storage temperature range	-65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

recommended operating conditions (see Note 2)

			BT648	SN74A	UNIT	
		MIN	MAX	MIN	MAX	UNII
Vcc	Supply voltage	4.5	5.5	4.5	5.5	V
VIH	High-level input voltage	2		2		V
V _{IL}	Low-level input voltage		0.8		0.8	V
VI	Input voltage	0	VCC	0	VCC	V
lOH	High-level output current		-24		-32	mA
lOL	Low-level output current		48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate		5		5	ns/V
TA	Operating free-air temperature	-55	125	-40	85	°C

NOTE 2: Unused or floating pins (input or I/O) must be held high or low.



SCBS466 - JANUARY 1991 - REVISED OCTOBER 1992

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETED	TEST CONDITIONS			Т	A = 25°0	;	SN54A	BT648	SN74ABT648		UNIT		
PARAMETER				MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNII		
VIK	V _{CC} = 4.5 V,	I _I = -18 mA				-1.2		-1.2		-1.2	V		
	$V_{CC} = 4.5 \text{ V},$	$I_{OH} = -3 \text{ mA}$		2.5			2.5		2.5				
V	V _{CC} = 5 V,	$I_{OH} = -3 \text{ mA}$		3			3		3		v		
VOH	V 45V	$I_{OH} = -24 \text{ mA}$		2			2				V		
	V _{CC} = 4.5 V	I _{OH} = -32 mA		2‡					2				
V	V 45V	I _{OL} = 48 mA				0.55		0.55					
VOL	V _{CC} = 4.5 V	I _{OL} = 64 mA				0.55‡				0.55	V		
	V _{CC} = 5.5 V,	•	Control inputs			±1		±1		±1			
ΙΙ	V _I = V _{CC} or GND		A or B ports			±100		±100		±100	μΑ		
lozн§	V _{CC} = 5.5 V,	V _O = 2.7 V	_			50		50		50	μΑ		
lozL§	V _{CC} = 5.5 V,	V _O = 0.5 V				-50		-50		-50	μΑ		
l _{off}	$V_{CC} = 0$,	V _I or V _O ≤ 4.5	V			±100				±100	μΑ		
ICEX	V _{CC} = 5.5 V,	V _O = 5.5 V	Outputs high			50		50		50	μΑ		
IO¶	V _{CC} = 5.5 V,	V _O = 2.5 V	_	-50	-100	-180	-50	-180	-50	-180	mA		
					Outputs high		1	250		250		250	μΑ
ICC	$V_{CC} = 5.5 \text{ V},$ $V_{I} = V_{CC} \text{ or GND}$	$I_{O}=0,$	Outputs low		24	30		30		30	mA		
	$\Lambda I = \Lambda CC$ of GMD		Outputs disabled		0.5	250		250		250	μΑ		
∆l _{CC} #	V _{CC} = 5.5 V, Other inputs at V _C	One input at 3	.4 V,			1.5		1.5		1.5	mA		
Ci	V _I = 2.5 V or 0.5 V	·	Control inputs								pF		
C _{io}	V _O = 2.5 V or 0.5 \	/	A or B ports								pF		

[†] All typical values are at $V_{CC} = 5 \text{ V}$.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

				V _{CC} = 5 V, T _A = 25°C		SN54ABT648		SN74ABT648	
				MAX	MIN	MAX	MIN	MAX	
fclock	ck Clock frequency								MHz
t _W	Pulse duration, CLK high or low								ns
t _{su}	Setup time, A or B before CLKAB↑ or CLKBA↑	Low							ns
t _h	Hold time, A or B after CLKAB↑ or CLKBA↑								ns



[‡] On products compliant to MIL-STD-883, Class B, this parameter does not apply.

 $[\]$ The parameters IOZH and IOZL include the input leakage current.

[¶] Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

[#]This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

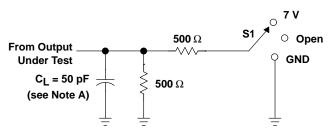
SCBS466 - JANUARY 1991 - REVISED OCTOBER 1992

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 2)

PARAMETER	FROM	TO (OUTDUT)	V _{CC} = 5 V, T _A = 25°C			SN54A	BT648	SN74ABT648		UNIT	
	(INPUT)	(OUTPUT)	MIN	TYP	MAX	MIN	MAX	MIN	MAX		
f _{max}										MHz	
^t PLH	A or B	B or A								ns	
^t PHL	AOIB	BOIA								115	
^t PLH	CLKBA or CLKAB	A or B								ns	
^t PHL	CLNBA OI CLNAB	7015								115	
^t PLH	SBA or SAB†	A or B								- ns	
^t PHL	(with A or B high)	AOIB									
^t PLH	SBA or SAB [†]	A or B								ns	
^t PHL	(with A or B low)									113	
^t PZH	 OEBA	A or B								ns	
^t PZL	OLBA	7015								113	
^t PHZ	OEBA	A or B								ns	
^t PLZ	OLBA	7010								113	
^t PZH	DIR	A or B								ns	
^t PZL	DIIX	AUD								113	
^t PHZ	DIR	A or B					·			ns	
tPLZ	DIK	AUD								115	

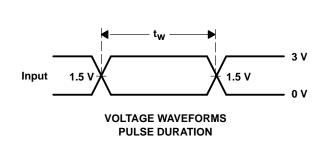
[†] These parameters are measured with the internal output state of the storage registers opposite to that of the bus input.

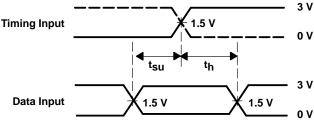


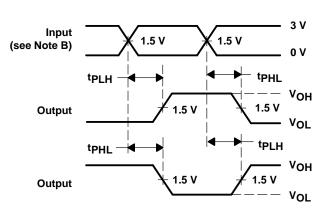


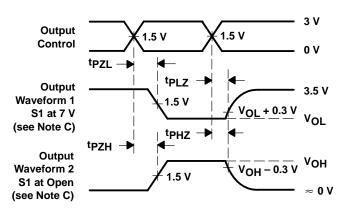
TEST	S1
tPLH/tPHL	Open
tPLZ/tPZL	7 V
tPHZ/tPZH	Open

LOAD CIRCUIT FOR OUTPUTS









VOLTAGE WAVEFORMS PROPAGATION DELAY TIMES INVERTING AND NONINVERTING OUTPUTS

ENABLE AND DISABLE TIMES

NOTES: A. C_L includes probe and jig capacitance.

- B. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \Omega$, $t_f \leq 2.5$ ns. $t_f \leq 2.5$ ns.
- C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 2. Load Circuit and Voltage Waveforms



PRODUCT PREVIEW

VOLTAGE WAVEFORMS SETUP AND HOLD TIMES

VOLTAGE WAVEFORMS LOW- AND HIGH-LEVEL ENABLING

IMPORTANT NOTICE

Texas Instruments (TI) reserves the right to make changes to its products or to discontinue any semiconductor product or service without notice, and advises its customers to obtain the latest version of relevant information to verify, before placing orders, that the information being relied on is current.

TI warrants performance of its semiconductor products and related software to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are utilized to the extent TI deems necessary to support this warranty. Specific testing of all parameters of each device is not necessarily performed, except those mandated by government requirements.

Certain applications using semiconductor products may involve potential risks of death, personal injury, or severe property or environmental damage ("Critical Applications").

TI SEMICONDUCTOR PRODUCTS ARE NOT DESIGNED, INTENDED, AUTHORIZED, OR WARRANTED TO BE SUITABLE FOR USE IN LIFE-SUPPORT APPLICATIONS, DEVICES OR SYSTEMS OR OTHER CRITICAL APPLICATIONS.

Inclusion of TI products in such applications is understood to be fully at the risk of the customer. Use of TI products in such applications requires the written approval of an appropriate TI officer. Questions concerning potential risk applications should be directed to TI through a local SC sales office.

In order to minimize risks associated with the customer's applications, adequate design and operating safeguards should be provided by the customer to minimize inherent or procedural hazards.

TI assumes no liability for applications assistance, customer product design, software performance, or infringement of patents or services described herein. Nor does TI warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right of TI covering or relating to any combination, machine, or process in which such semiconductor products or services might be or are used.

Copyright © 1996, Texas Instruments Incorporated